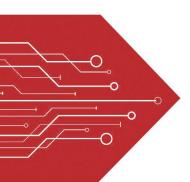
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data sheet





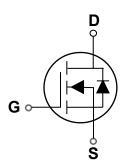








SOT-23-3L



Features

- 20 V, 6A, RDS(ON)=18mΩ@VGS=4.5V
- Improved dv/dt capability
- Fast switching
- Green Device Available

Applications

- Notebook
- Load Switch
- Hend-Held Instruments

BVDSS	RDSON	ID
20V	18mΩ	6A

Absolute Maximum Ratings Tc=25℃ unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	20	V
V _{GS}	Gate-Source Voltage	±12	V
	Drain Current – Continuous (T _C =250)	6.0	А
ID	Drain Current – Continuous (T _C =1000)	4.0	А
I _{DM}	Drain Current – Pulsed ¹	24	А
.	Power Dissipation (T _C =250)	1.56	W
P _D	Power Dissipation – Derate above 250	0.012	W/ C
T _{STG}	Storage Temperature Range	-55 to 150	С
TJ	Operating Junction Temperature Range	-55 to 150	С

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit
Reja	Thermal Resistance Junction to ambient		80	c/ W





Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA			1	V
△BV _{DSS} /△T _J	BV _{DSS} Temperature Coefficient Reference to 250 , I _D =1mA			0.02		V/ C
	Drain-Source Leakage Current	V _{DS} =20V , V _{GS} =0V , T _J =250			1	uA
I _{DSS} Drain-Source Leakage Current		V _{DS} =16V , V _{GS} =0V , T _J =1250			10	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±12V , V _{DS} =0V			±100	nA

On Characteristics

R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V , I _D =5A		18	26	mΩ
T (DS(ON)		V _{GS} =2.5V , I _D =4A		24	40	
V _{GS(th)}	Gate Threshold Voltage	\\ _\\	0.4	0.7	1.1	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		2		mV/ C
gfs	Forward Transconductance	V _{DS} =10V , I _S =4A		9.5		S

Dynamic and switching Characteristics

Qg	Total Gate Charge ^{2,3}		 5.8	
Qgs	Gate-Source Charge ^{2, 3}	V_{DS} =10V , V_{GS} =4.5V , I_{D} =4A	 0.6	 nC
Q_{gd}	Gate-Drain Charge ^{2, 3}		 2	
T _{d(on)}	Turn-On Delay Time ^{2,3}		 5.0	
Tr	Rise Time ^{2,3}	V_{DD} =10V , V_{GS} =4.5V , R_{G} =25 Ω	 14.4	 nS
T _{d(off)}	Turn-Off Delay Time ^{2,3}	I _D =1A	 30.0	 113
T _f	Fall Time ^{2,3}		 9.2	
Ciss	Input Capacitance		 600	
Coss	Output Capacitance	V_{DS} =10V , V_{GS} =0V , F=1MHz	 70	 pF
Crss	Reverse Transfer Capacitance		 45	

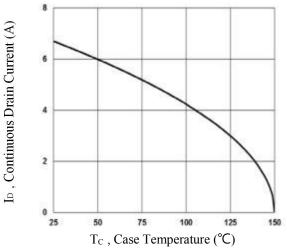
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	\/-=\/-=0\/ Force Current			6.0	Α
Іѕм	Pulsed Source Current	V _G =V _D =0V , Force Current			12	Α
V _{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =1A , T _J =250			1.2	V

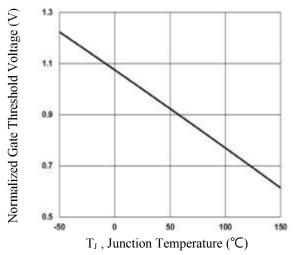
Note:

- Repetitive Rating: Pulsed width limited by maximum junction temperature. 1.
- The data tested by pulsed , pulse width \leq 300 us , duty cycle \leq 2%.
- Essentially independent of operating temperature.

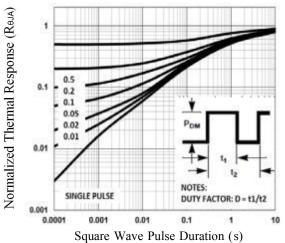




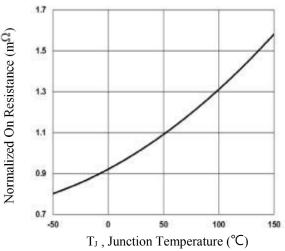
Continuous Drain Current vs. T_c Fig. 1



Normalized V_{th} vs. $\ T_{\text{J}}$ Fig. 3



Normalized Transient Impedance Fig. 5



Normalized RDSON vs. T_J Fig. 2

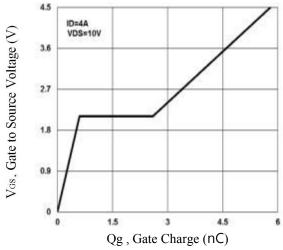


Fig. 4 Gate Charge Waveform

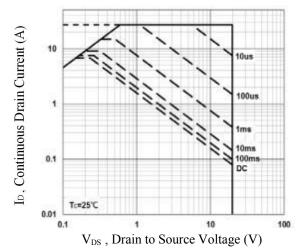
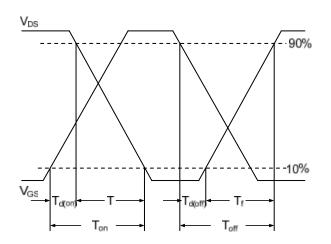


Fig. 6 Maximum Safe Operation Area





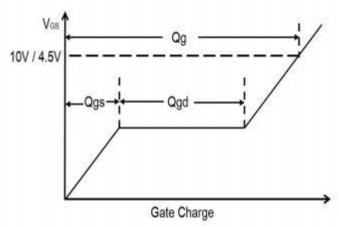
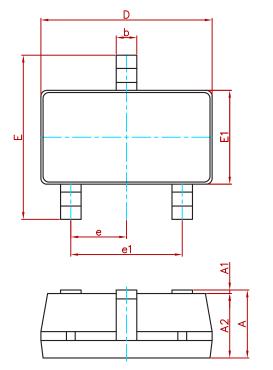


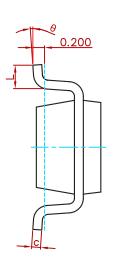
Fig. 7 Switching Time Waveform

Fig. 8 Gate Charge Waveform



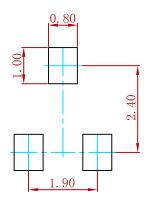
PACKAGE MECHANICAL DATA





Symbol	Dimensions In Millimeter		Dimension	s In Inches
Syllibol	Min.	Max.	Min.	Max.
Α	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
С	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
е	0.950(BSC)		0.037	(BSC)
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
А	0°	۵°	N°	۵°

Suggested Pad Layout



- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
AO3420	SOT-23-3L	3000



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STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 IPS60R360PFD7SAKMA1
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